

Manufacturer:**Date:** 29/09/2014

BoardSpecifications					
File name	CIAA-NXP v1	Material	FR4		
		Layernumber	4		
Quantity		Thickness	1.684mm		
Size	138.55 x 86.23 mm	Finish	HAL(Lead Free)		
Soldermask	Black	Silkscreen	White		
Copperthickness	OuterLayer	1 oz			
	InnerLayer	1 oz			
Stack Up					
Layer		Description	Thickness		File name
Number	Name		[oz/mil]	[mm]	
1	Top	Signal	1 oz	0.035 mm	ciaa-nxp-F_Cu.gtl
		Dielectric	10.7 mil	0.272 mm	
2	InternalPlane1	Signal	1 oz	0.035 mm	ciaa-nxp-Inner1_Cu.gbr
		Dielectric	39.3mil	1 mm	
3	InternalPlane2	signal	1 oz	0.035 mm	Iciaa-nxp-Inner2_Cu.gbr
		Dielectric	10.7 mil	0.272 mm	
4	Bottom	Signal	1 oz	0.035 mm	ciaa-nxp-B_Cu.gbl
Total boardthickness				1.684 mm	

Files gerber	
File name	Description
ciaa-nxp-F_Cu.gtl	Top signal layer
ciaa-nxp-Inner1_Cu.gbr	Plane GND and signal
ciaa-nxp-Inner2_Cu.gbr	PlaneVcc and signal
ciaa-nxp-B_Cu.gbl	Bottom signal layer
ciaa-nxp-F_Silks.gto	Top silkscreen
ciaa-nxp-B_Silks.gbo	Bottom silkscreen
ciaa-nxp-F_Mask.gts	Top solder Mask
ciaa-nxp-B_Mask.gbs	Bottom solderMask
ciaa-nxp-F_Paste.gtp	Top solder Past
ciaa-nxp-B_Paste.gbp	Bottom solder Past
ciaa-nxp.drl	drill
ciaa-nxp-Edge_Cuts.gbr	Board outline